

ABSTRACT OF THE DISCLOSURE

A spring contact for establishing electrical contact between a lead element of an IC device and a substrate. The spring contact generally comprises a contact portion and a base portion. The contact portion, which generally comprises a coil-type compression spring, is configured to engage and resiliently bias against a lead element of the IC device. The spring contact is disposed in a mating aperture formed in the substrate. The base portion of the spring contact is configured to secure the spring contact within the mating aperture and to establish electrical contact with the substrate. A plurality of such spring contacts and mating apertures may be arranged on the substrate in an array corresponding to the pinout of the IC device. A clamping element secures the IC device to the substrate and biases the IC device against the spring contacts.

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